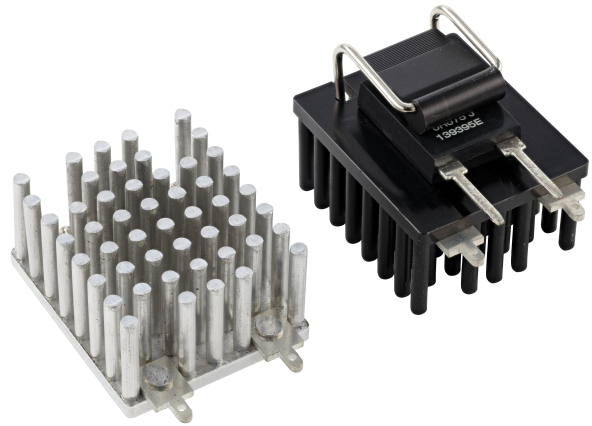


P Series Heatsinks

Forged Pin Fin heatsink for TO-220, TO-247 and TO-264 devices

Ohmite introduces the P series forged pin-fin heatsink (Pat. Pending). The P series heat sinks offer an all-in-one solution combining a compact design with a universal cam clip system for TO-220, TO-247, TO-264 package devices. This powerful forged pin heatsink is designed to be thru-hole soldered to the PCB board. The forged pin design allows forced convection cooling in multiple directions.

The pin fin design allows for a larger surface area creating minimum thermal flow impedance. The P series is the ideal type of heat sink for high power and small size (1U or 2U) electronic packaging with natural and forced convection cooling.



SERIES SPECIFICATIONS

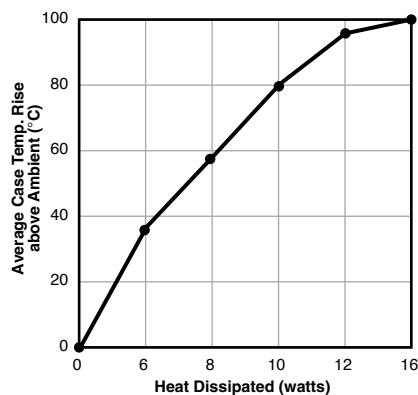
Heatsink Part Number	Surface Area (in ² / mm ²)	Weight (oz./g)	Length (in / mm)	R _{θc-a} * (°C/W)
PA-T2X-38E	13.4 / 8,675	0.7 / 20	1.18 / 30	7.46
PV-T2X-38E	13.4 / 8,675	0.7 / 20	1.18 / 30	8.07

*--Thermal Resistance is in open space @14 W power dissipation

CHARACTERISTICS

Heat sink	AL1070
Spring clip	Music Wire, Per ASTM A228 with bright nickel plating
Solder feet	Brass with pure tin or nickel. RoHS compliant
Interface thermal resistance	For improvement, use thermal joint compound, 0.005 Grafoil (TGon 800 by Laird), or phase change material (Hi-Flow by Bergquist)
Insulator	Sil-Pad 900-S, K6 800-S and K10 by Bergquist

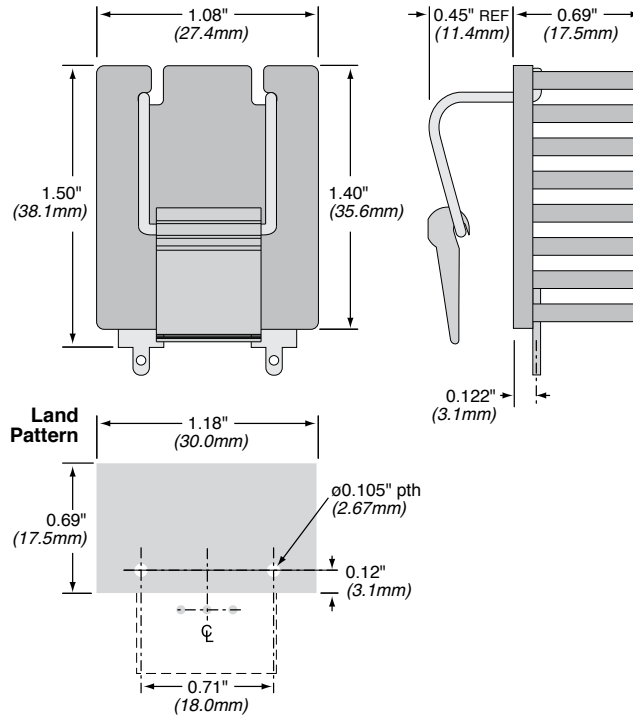
Thermal Performance



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DIMENSIONS



ORDERING INFORMATION

P A - T 2 X - 3 8 E

Series	Finish	Package	Height	RoHS
P	A = anodized V = degreased	TO- devices	(mm)	Compliant